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<th>Ref.</th>
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<th>Silkscreen</th>
<th>S Mask</th>
<th>P Mask</th>
<th>Assembly</th>
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- Board No.: PMP7451
- Ref.: A
- Copper Layer Name: L1
- Silkscreen: Top, Internal, Bot
- S Mask: Top, Bot
- P Mask: Top, Bot
- Assembly: Top, Bot
- Drill Drawing: Empty

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**Notes:**
- Date (Start Date): Empty
- Version: PMP7451.PCB
- Engineer: B. KING
- Date Digit: R. Smith
- Revision Date: Modification Date
- Software: PADS

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**Diagram:**
- Illustration of a printed circuit board (PCB) layout with various components and their corresponding connections.
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<th>TEXAS INSTRUMENTS</th>
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NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:
   - ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS
   - AND SOLDERMASK, COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET
   - UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.

2. BASE LAMINATE:
   - PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR
   - EQUIVALENT, W/Fg =130 Deg C OR HIGHER; MINIMUM COMPOSITION TEMP (%) OF 320 Deg c.
   - GLASS EPOXY RESIN COPPER CLAD IN ACCORDANCE WITH 4 LAYER STACK-UP,
   - COMPLIANT WITH LEAD FREE PROCESS.

3. SOLDERMASK:
   - SOLDERMASK: COVER BARE COPPER (SMOKE) USING LIQUID PHOTOIMAGEABLE SOLDERMASK IN
   - ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE
   - PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINISH ASSEMBLY
   - AS A RESULT.

4. TOLERANCES:
   - UNLESS OTHERWISE SPECIFIED PCB TOLERANCES
   - SHALL BE +/- .005 INCHES. HOLE DIAMETERS SHALL BE +/- .003 INCHES.

5. PLATING:
   - HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0034) MIN. THK MIN.
   - THICK COPPER.

6. FINISH:
   - PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREPARED, IMMERSION TIN OR SnAgCu
   - WITH RMA FLUX, 0.003" to .005" THICK ALL EXPOSED AREAS
   - AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.

7. LEGEND:
   - IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.

8. MARKINGS:
   - BOARD MUST BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
   - BOAR IS LOCATION OPTIONAL.

9. WORKMANSHIP:
   - BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.

10. DOCUMENTATION:
    - PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS
    - INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.

11. DRILL SIZES:
    - HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFT PLATING UNLESS OTHERWISE NOTED.

12. PANEL BORDER:
    - ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS
    - MUST BE COVERED WITH SOLDERMASK.

13. PROCESS CHANGES:
    - NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION
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